DATE: 08/13/2004

cosmo

**ELECTRONICS CORPORATION** 

SMD LED:

**KL-670YXX** 

NO. 61L40002

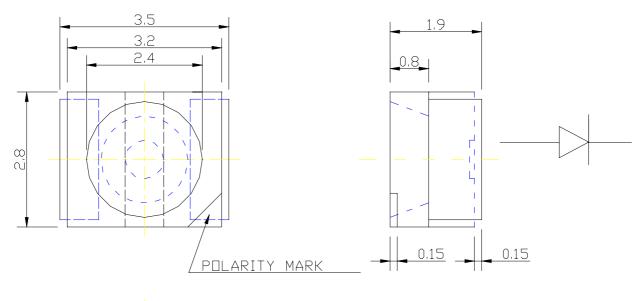
REV.

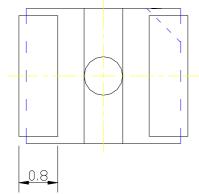
SHEET 1 OF 9

1

**UNIT:MM** 

**TOLERANCE: ±0.25** 





Part No.	Emitting Color	Material	Lens Type	I (IF=2 MIN (mcd)	v 0mA) TYP (mcd)	Viewing Angle 2 θ 1/2
KL-670YXX	Yellow	GaAsP	Water Clear	8	15	120°

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SHEET 2 OF 9

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Absolute maximum ratings (TA=25°C)		Y Yellow (GaAsP)	Unit
Reverse voltage	$V_R$	5	V
Forward current	IF	30	mA
Forward current(Peak)	Ifp	100	mA
1/10 Duty Cycle,0.1ms Pulse Width			
Power dissipation	Pd	50	mW
LED LAMPS:			
Operating temperature	Тор	<b>-40∼+85</b>	$^{\circ}$ C
Storage temperature	Tst	-40~+85	$^{\circ}$ C
LED DISPLAYS:			
Operating temperature	TA	-40~+85	$^{\circ}$
Storage temperature	Tstg	-40~+85	$^{\circ}$

Operating characteristics (TA=25°C)		Y Yellow (GaAsP)	Unit
Forward voltage(typ.) IF=20mA	VF	2.1	V
Forward voltage(max.) IF=20mA	$\mathbf{V}_{\mathbf{F}}$	2.5	V
Reverse current(max.) V <sub>R</sub> =5V	Ir	10	uA
Wavelength at dominant emission(typ.)	λъ	590	nm
IF=20mA Wavelength at peak emission(typ.)	λР	589	nm
I <sub>F</sub> =20mA Spectral line half-width	Δλ	35	nm
IF=20mA Capacitance VF=0V,f=1MHz	C	10	pF

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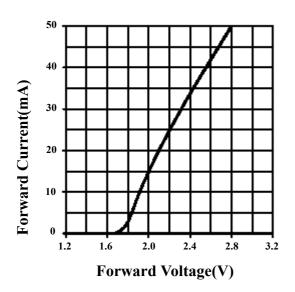
SMD LED:

**KL-670YXX** 

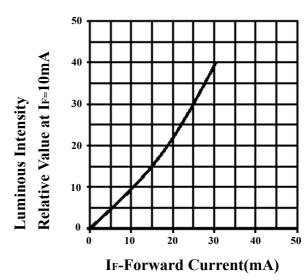
NO.61L40002

REV.

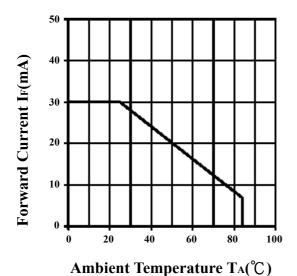
1 **SHEET 3 OF 9** 



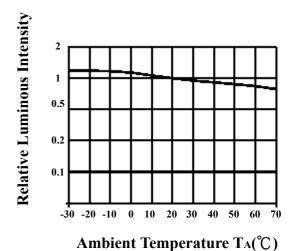
Forward Current Vs. **Forward Voltage** 



Luminous Intensity Vs. **Forward Current** 



**Forward Current Derating Curve** 



Luminous Intensity Vs. **Ambient Temperature** 

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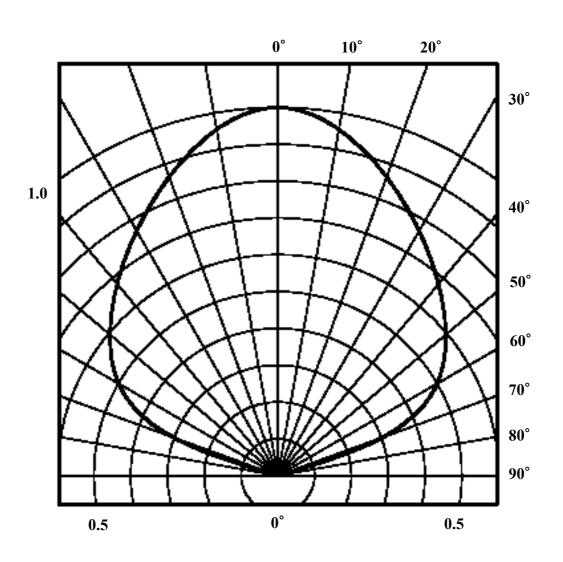
SMD LED:

**KL-670YXX** 

NO. 61L40002 REV.

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View Angle 2  $\theta$ 1/2=120°

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**ELECTRONICS CORPORATION** 

SMD LED:

**KL-670YXX** 

NO. 61L40002

REV.

SHEET 5 OF 9

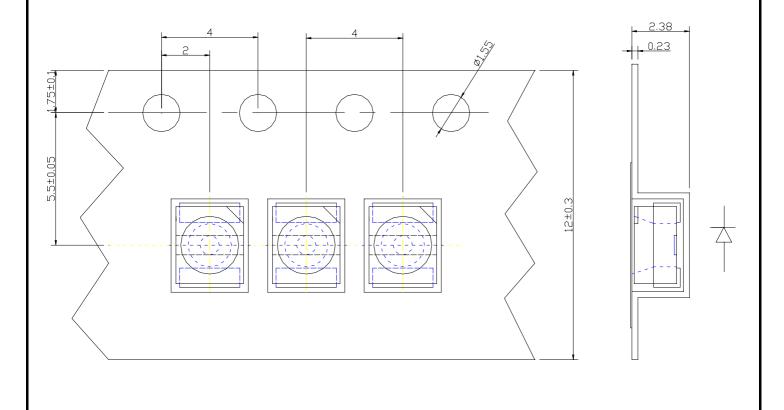
1

**UNIT:MM** 

**TOLERANCE: ±0.25** 

TYPE PACKAGE:1500 OR 1000PCS/REEL

REEL"T":18mmTYP



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SMD LED:

**KL-670YXX** 

NO. 61L40002

REV.

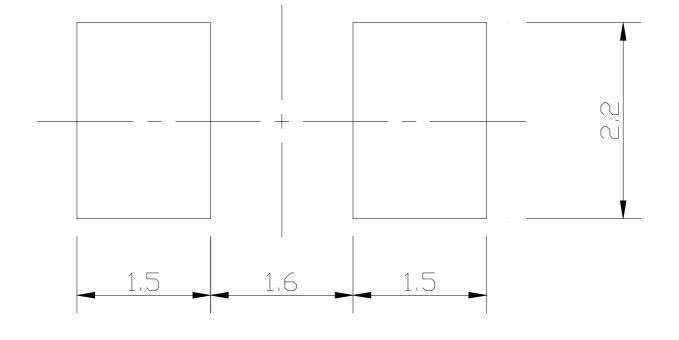
SHEET 6 OF 9

1

**UNIT:MM** 

The following soldering patterns are recommended for reflow-soldering:

For reflow soldering



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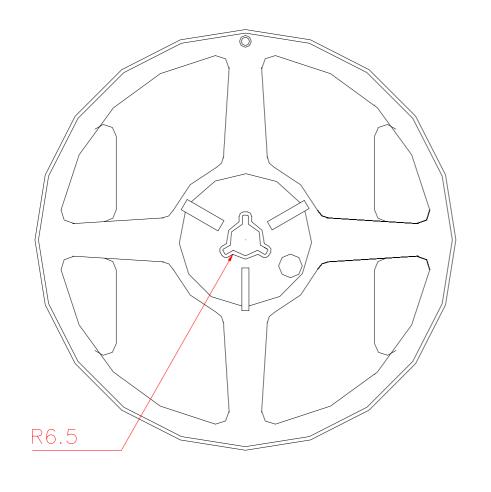
REV.

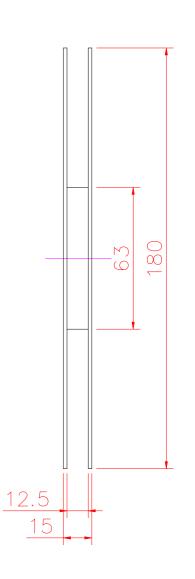
SHEET 7 OF 9

1

**UNIT:MM** 

**TOLERANCE: ±0.25** 





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SMD LED:

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REV.

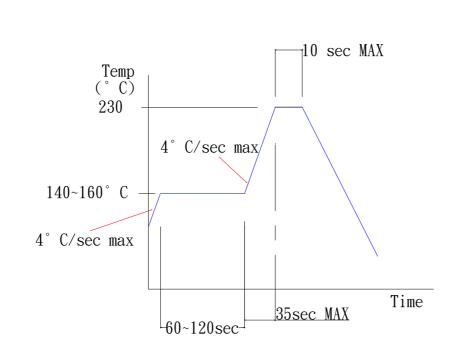
SHEET 8 OF 9

1

#### **SOLDERING**

# SMT REFLOW SOLDERING INSTRUCTIONS





SOLDERING INSRTUCTIONS							
TYPES	DIP AND WAVE SOLDERING			IRON SOLDERING(WITH 1.5mm IRON TIP)			
	TEMPERATURE OF THE SOLDERING BATH	MAXLMUM SOLDERING TIME	DISTANCE FORM SOLDER JOINT TO CASE	TEMPERATURE OF SOLDERING IRON	MAXLMUM SOLDERING TIME	DISTANCE FROM SOLDER JOINT TO CASE	
LEDS	<b>≦260</b> ℃	3S	>2mm	<b>≦260</b> ℃	3S	>2mm	
	<b>≦260</b> ℃	5S	>4mm	<b>≦260</b> ℃	5S	>4mm	
DISPLAYS	<b>≦260</b> ℃	3S	>2mm	<b>≦260</b> ℃	3S	>2mm	
DISPLAYS	<b>≦260</b> ℃	3S	>2mm	<b>≦260</b> ℃	3S	>2mm	

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REV.

SHEET 9 OF 9

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#### **SMD HANDLING AND APPLICATION PRECAUTIONS**

#### **STORAGE**

(1.1)It is recommended to store the devices in accordance with the following conditions:

Humidity: 60%RH Max.

Temperature:  $5^{\circ}\text{C} \sim 30^{\circ}\text{C}$  ( $41^{\circ}\text{F} \sim 86^{\circ}\text{F}$ )

(1.2)Shelf life in sealed bag: 12 month at  $<5^{\circ}\text{C} \sim 30^{\circ}\text{C}$  and <30%RH.

After the package is opened, the products should be used within 72hrs.

Or they should be kept at  $\leq 20\%\text{RH}$  in zip -locked sealed bags.

#### DRY PACK AND BAKING

SMD LEDs are MOISTURE SENSITIVE devices. Avoid absorbing moisture at any time during transportation and/or storage. It is recommended to bake before soldering when the pack is unsealed after 72 hrs, or any suspicious moisture being found. Bake devices in accordance with the following conditions:

- (a)  $60\pm3^{\circ}$ C x (12~24hrs) and <5%RH, taped reel type
- (b)  $100\pm3^{\circ}$ C x (45min~1hr), loose packing type, or
- (c)  $130\pm3^{\circ}$ C x (15~30min), loose packing type

#### **ELECTRIC STATIC DISCHARGE(ESD) PROTECTION**

Materials with GaN, InGaN, AlInGaP are STATIC SENSITIVE devices. They will be packed in anti-static bags. ESD protection must be deliberatively observed from the initial design stage. The static -electric discharge may result in severe malfunction of the devices. In the events of manual working in process, make sure the devices are well protected from ESD at any time. Surge before and during handling products.